

#### FEATURES

- Non Punch Through Silicon
- Isolated Copper Baseplate with  $AL_2O_3$  Substrate
- Low Inductance Internal Construction

#### APPLICATIONS

- High Power Inverters
- Motor Controllers
- Induction Heating
- Resonant Converters

The Powerline range of high power modules includes dual, half bridge and single switch configurations covering voltages from 600V to 3300V and currents up to 4800A.

The GP800NSS33 is a single switch 3300V, n channel enhancement mode, insulated gate bipolar transistor (IGBT) module. The IGBT has a wide reverse bias safe operating area (RBSOA) ensuring reliability in demanding applications.

The module incorporates an electrically isolated base plate and low inductance construction enabling circuit designers to optimise circuit layouts and utilise earthed heat sinks for safety.

#### ORDERING INFORMATION

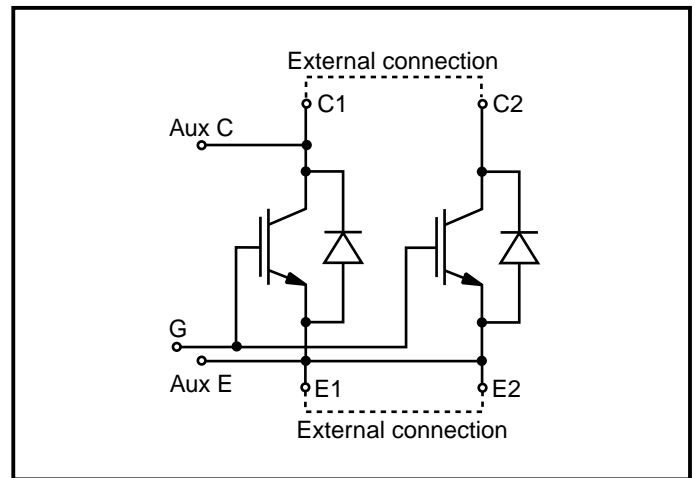
Order As:

**GP800NSS33**

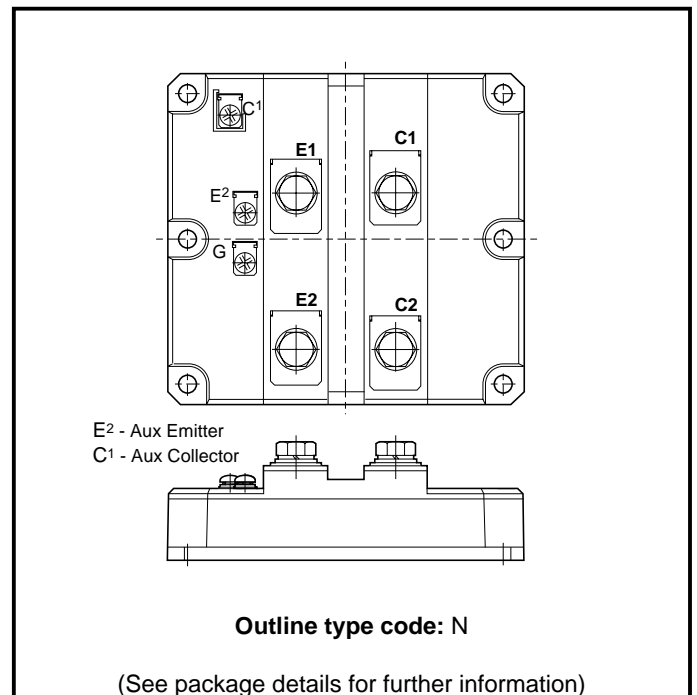
Note: When ordering, please use the whole part number.

#### KEY PARAMETERS

$V_{CES}$		<b>3300V</b>
$V_{CE(sat)}$	<b>(typ)</b>	<b>3.6V</b>
$I_C$	<b>(max)</b>	<b>800A</b>
$I_{C(PK)}$	<b>(max)</b>	<b>1600A</b>



**Fig. 1 Single switch circuit diagram**



**Fig. 2 Electrical connections - (not to scale)**

## ABSOLUTE MAXIMUM RATINGS

Stresses above those listed under 'Absolute Maximum Ratings' may cause permanent damage to the device. In extreme conditions, as with all semiconductors, this may include potentially hazardous rupture of the package. Appropriate safety precautions should always be followed. Exposure to Absolute Maximum Ratings may affect device reliability.

$T_{\text{case}} = 25^{\circ}\text{C}$  unless stated otherwise

Symbol	Parameter	Test Conditions	Max.	Units
$V_{\text{CES}}$	Collector-emitter voltage	$V_{\text{GE}} = 0\text{V}$	3300	V
$V_{\text{GES}}$	Gate-emitter voltage	-	$\pm 20$	V
$I_{\text{C}}$	Continuous collector current	$T_{\text{case}} = 70^{\circ}\text{C}$	800	A
$I_{\text{C(PK)}}$	Peak collector current	1ms, $T_{\text{case}} = 110^{\circ}\text{C}$	1600	A
$P_{\text{max}}$	Max. transistor power dissipation	$T_{\text{case}} = 25^{\circ}\text{C}$ , $T_{\text{j}} = 150^{\circ}\text{C}$	8.3	kW
$V_{\text{isol}}$	Isolation voltage	Commoned terminals to base plate. AC RMS, 1 min, 50Hz	6	kV

## THERMAL AND MECHANICAL RATINGS

Symbol	Parameter	Test Conditions	Min.	Max.	Units
$R_{\text{th(j-c)}}$	Thermal resistance - transistor	Continuous dissipation - junction to case	-	15	$^{\circ}\text{C}/\text{kW}$
$R_{\text{th(j-c)}}$	Thermal resistance - diode	Continuous dissipation - junction to case	-	30	$^{\circ}\text{C}/\text{kW}$
$R_{\text{th(c-h)}}$	Thermal resistance - case to heatsink (per module)	Mounting torque 5Nm (with mounting grease)	-	8	$^{\circ}\text{C}/\text{kW}$
$T_{\text{j}}$	Junction temperature	Transistor	-	125	$^{\circ}\text{C}$
		Diode	-	125	$^{\circ}\text{C}$
$T_{\text{stg}}$	Storage temperature range	-	-40	125	$^{\circ}\text{C}$
-	Screw torque	Mounting - M6	-	5	Nm
		Electrical connections - M4	-	2	Nm
		Electrical connections - M8	-	10	Nm

**ELECTRICAL CHARACTERISTICS**
 $T_{case} = 25^{\circ}\text{C}$  unless stated otherwise.

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$I_{CES}$	Collector cut-off current	$V_{GE} = 0\text{V}, V_{CE} = V_{CES}$	-	-	2	mA
		$V_{GE} = 0\text{V}, V_{CE} = V_{CES}, T_{case} = 125^{\circ}\text{C}$	-	-	70	mA
$I_{GES}$	Gate leakage current	$V_{GE} = \pm 20\text{V}, V_{CE} = 0\text{V}$	-	-	12	$\mu\text{A}$
$V_{GE(TH)}$	Gate threshold voltage	$I_C = 120\text{mA}, V_{GE} = V_{CE}$	4	-	7.5	V
$V_{CE(sat)}$	Collector-emitter saturation voltage	$V_{GE} = 15\text{V}, I_C = 800\text{A}$	-	3.6	4.3	V
		$V_{GE} = 15\text{V}, I_C = 800\text{A}, T_{case} = 125^{\circ}\text{C}$	-	4.5	5	V
$I_F$	Diode forward current	DC	-	-	800	A
$I_{FM}$	Diode maximum forward current	$t_p = 1\text{ms}$	-	-	1600	A
$V_F$	Diode forward voltage	$I_F = 800\text{A}$	-	2.3	2.9	V
		$I_F = 800\text{A}, T_{case} = 125^{\circ}\text{C}$	-	2.4	3	V
$C_{ies}$	Input capacitance	$V_{CE} = 25\text{V}, V_{GE} = 0\text{V}, f = 1\text{MHz}$	-	200	-	nF
$L_M$	Module inductance	-	-	15	-	nH

## ELECTRICAL CHARACTERISTICS

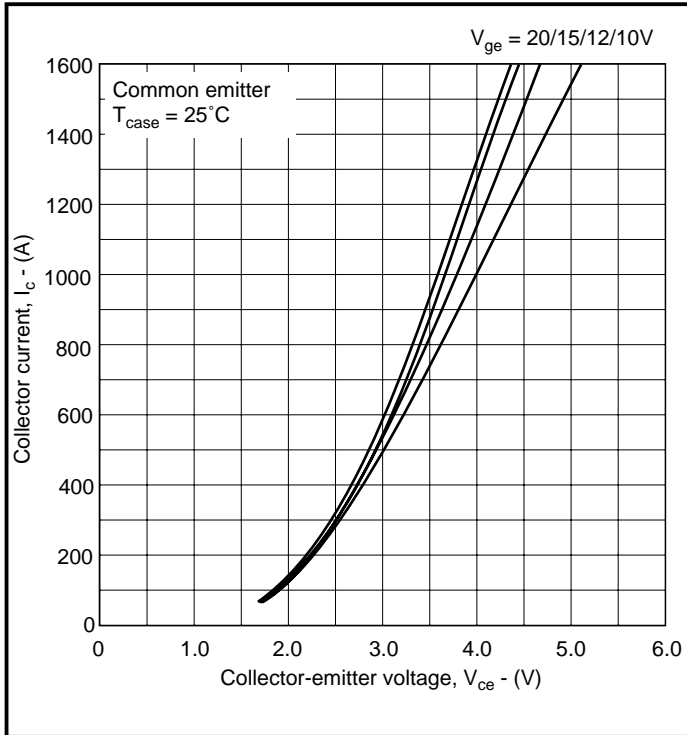
 $T_{\text{case}} = 25^{\circ}\text{C}$  unless stated otherwise

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$t_{\text{d(off)}}$	Turn-off delay time	$I_{\text{C}} = 800\text{A}$	-	3.2	-	$\mu\text{s}$
$t_{\text{f}}$	Fall time	$V_{\text{GE}} = \pm 15\text{V}$	-	0.7	-	$\mu\text{s}$
$E_{\text{OFF}}$	Turn-off energy loss	$V_{\text{CE}} = 1800\text{V}$	-	1	-	J
$t_{\text{d(on)}}$	Turn-on delay time	$R_{\text{G(ON)}} = 3.3\Omega$	-	1.1	-	$\mu\text{s}$
$t_{\text{r}}$	Rise time	$R_{\text{G(OFF)}} = 6.8\Omega$	-	0.4	-	$\mu\text{s}$
$E_{\text{ON}}$	Turn-on energy loss	$C_{\text{GE}} = 440\text{nF}$ , $L \sim 100\text{nH}$	-	1.2	-	J
$Q_{\text{rr}}$	Diode reverse recovery charge	$I_{\text{F}} = 800\text{A}$ , $V_{\text{R}} = 1800\text{V}$ ,	-	750	-	$\mu\text{C}$
$I_{\text{rr}}$	Diode reverse current	$di_{\text{F}}/dt = 3600\text{A}/\mu\text{s}$	-	400	-	A
$E_{\text{REC}}$	Diode reverse recovery energy		-	0.45	-	J

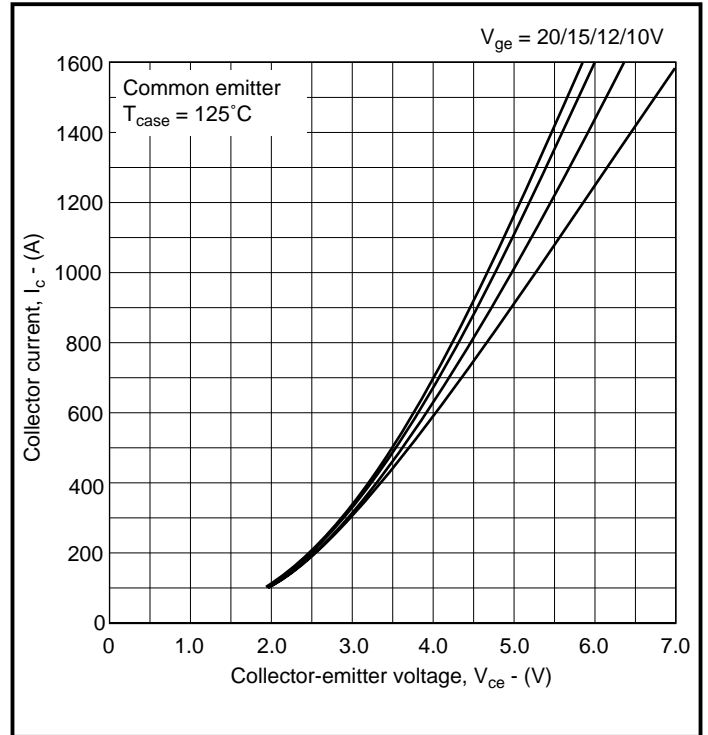
 $T_{\text{case}} = 125^{\circ}\text{C}$  unless stated otherwise

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$t_{\text{d(off)}}$	Turn-off delay time	$I_{\text{C}} = 800\text{A}$	-	3.4	-	$\mu\text{s}$
$t_{\text{f}}$	Fall time	$V_{\text{GE}} = \pm 15\text{V}$	-	1.1	-	$\mu\text{s}$
$E_{\text{OFF}}$	Turn-off energy loss	$V_{\text{CE}} = 1800\text{V}$	-	1.5	-	J
$t_{\text{d(on)}}$	Turn-on delay time	$R_{\text{G(ON)}} = 3.3\Omega$	-	1.1	-	$\mu\text{s}$
$t_{\text{r}}$	Rise time	$R_{\text{G(OFF)}} = 6.8\Omega$	-	0.5	-	$\mu\text{s}$
$E_{\text{ON}}$	Turn-on energy loss	$C_{\text{GE}} = 440\text{nF}$ , $L \sim 100\text{nH}$	-	1.5	-	J
$Q_{\text{rr}}$	Diode reverse recovery charge	$I_{\text{F}} = 800\text{A}$ , $V_{\text{R}} = 1800\text{V}$ ,	-	800	-	$\mu\text{C}$
$I_{\text{rr}}$	Diode reverse current	$di_{\text{F}}/dt = 3000\text{A}/\mu\text{s}$	-	650	-	A
$E_{\text{REC}}$	Diode reverse recovery energy		-	0.7	-	J

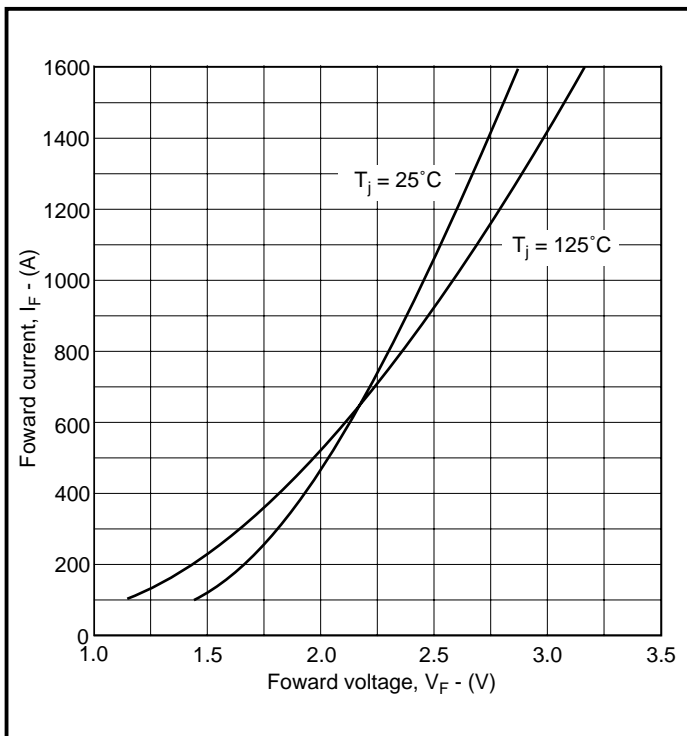
**TYPICAL CHARACTERISTICS**



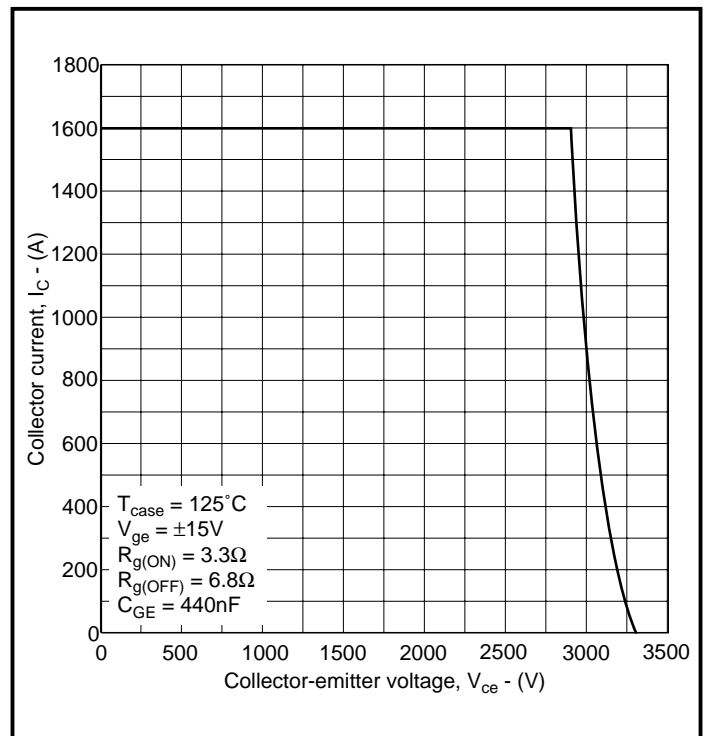
**Fig.3 Typical output characteristics**



**Fig.4 Typical output characteristics**



**Fig.5 Diode typical forward characteristics**



**Fig.6 Reverse bias safe operating area**

Caution: This device is sensitive to electrostatic discharge. Users should follow ESD handling procedures.

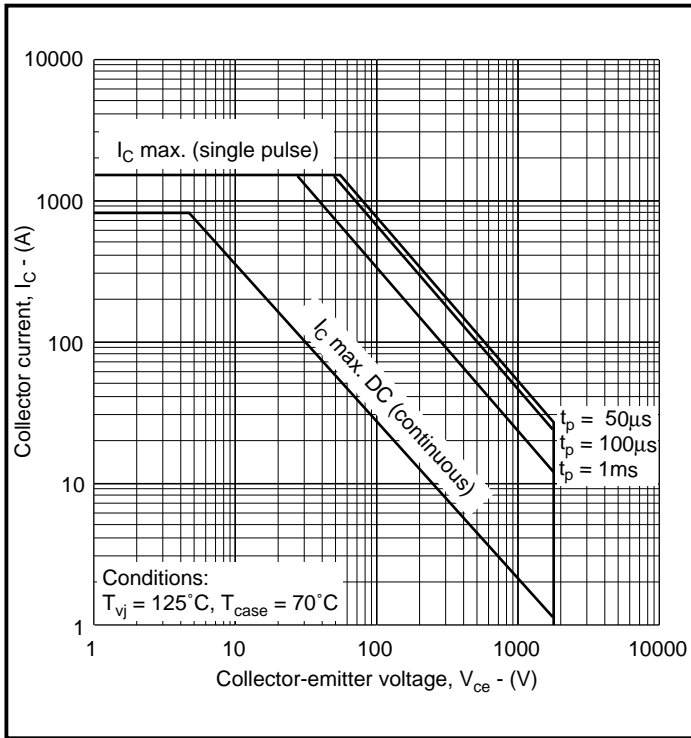


Fig.7 Forward bias safe operating area

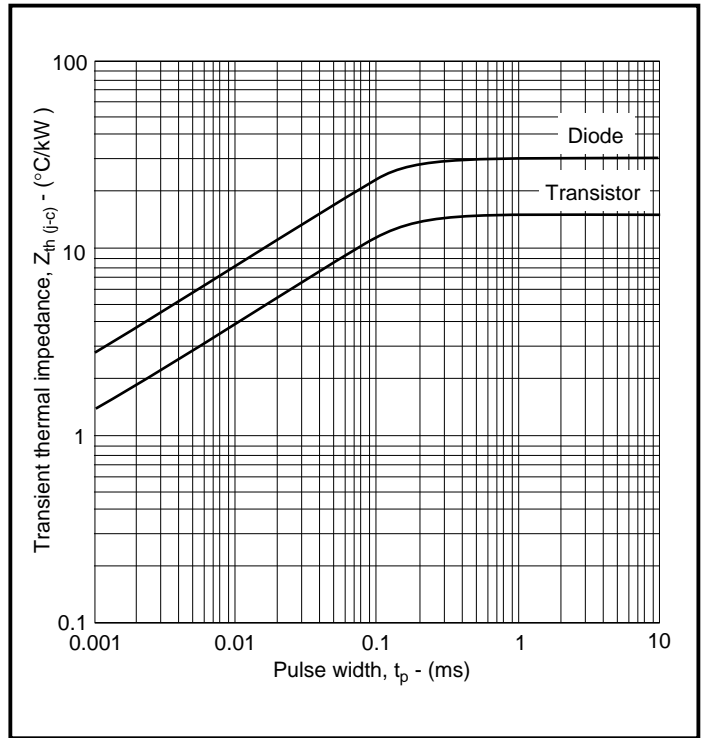


Fig.8 Transient thermal impedance

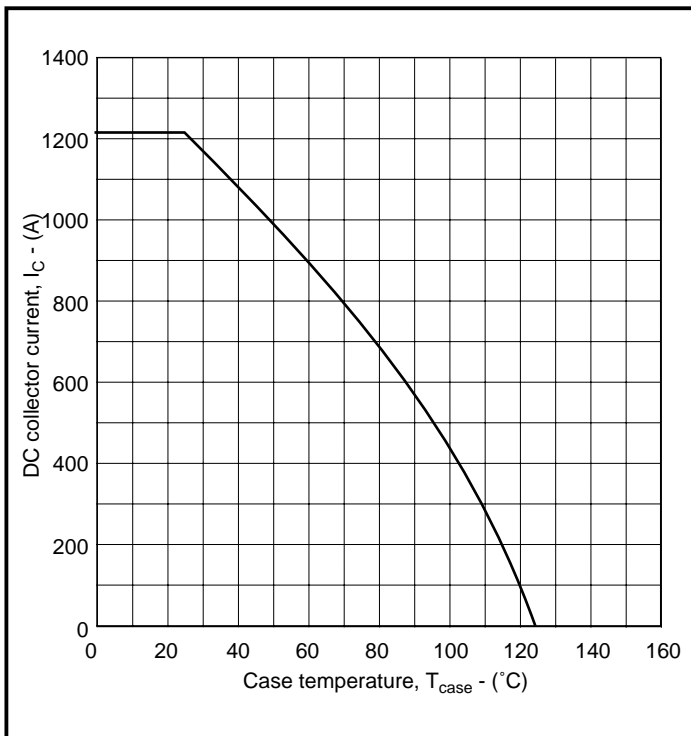


Fig.9 DC current rating vs case temperature

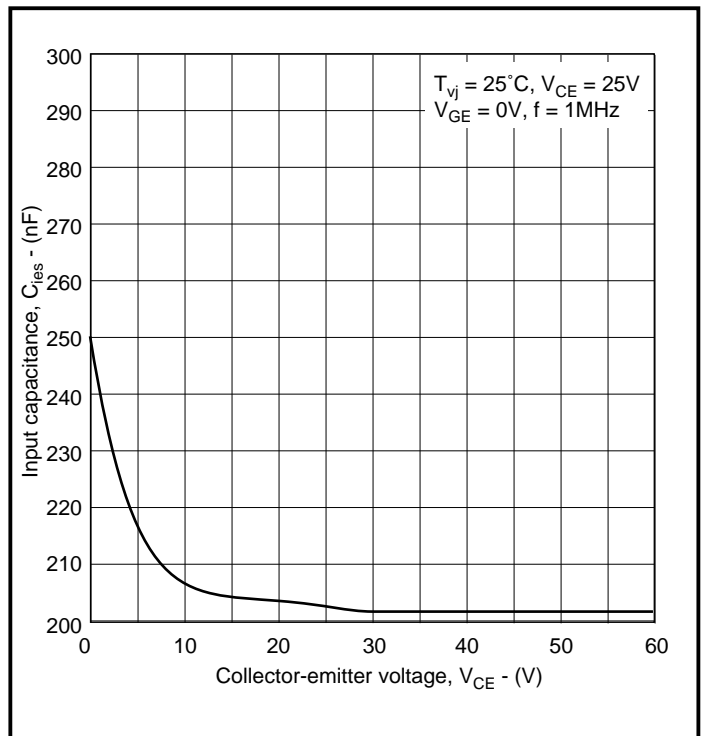
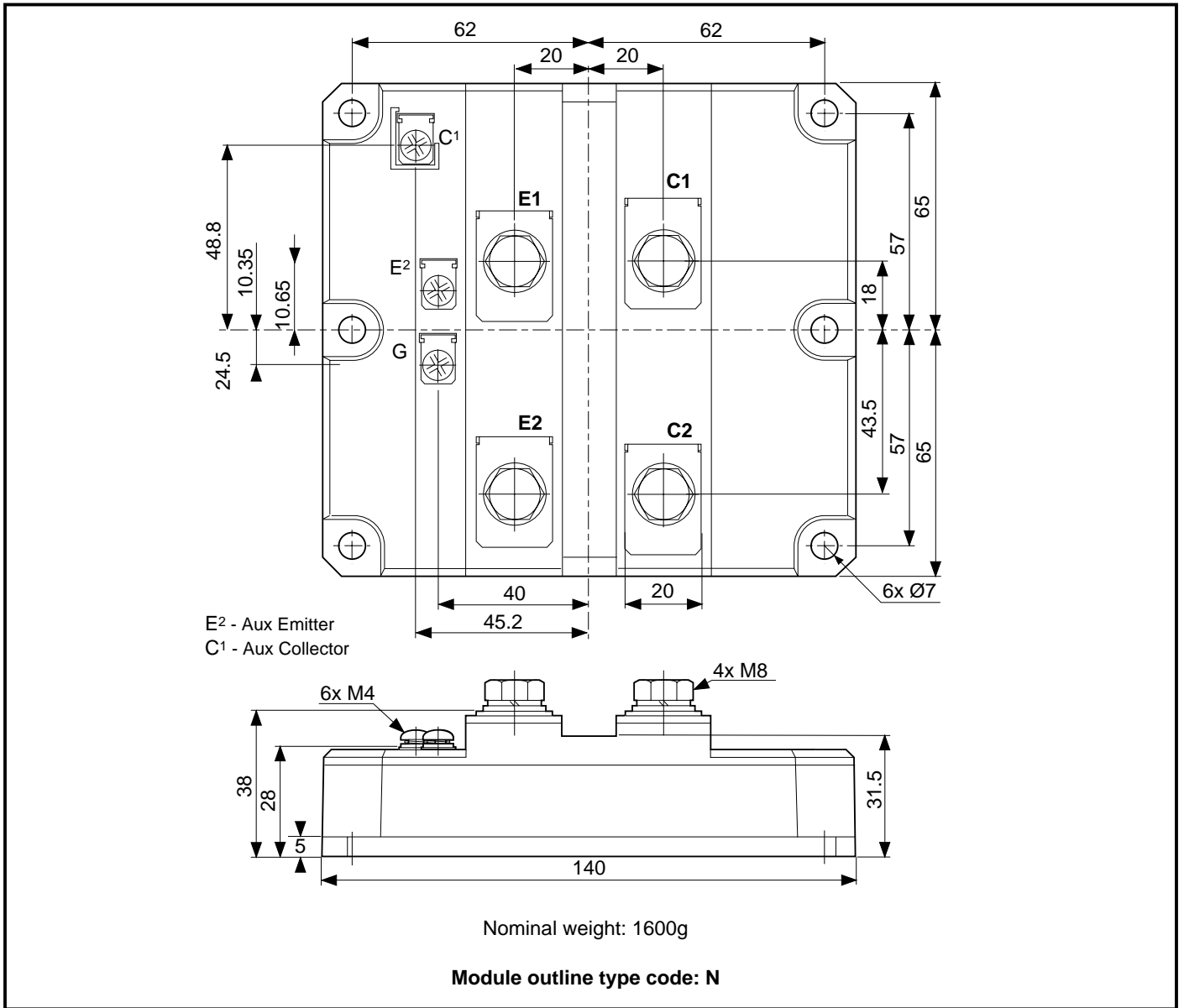


Fig.10 Typical input capacitance

**PACKAGE DETAILS**

For further package information, please visit our website or contact your nearest Customer Service Centre. All dimensions in mm, unless stated otherwise. DO NOT SCALE.



## ASSOCIATED PUBLICATIONS

Title	Application Note Number
Electrostatic handling precautions	AN4502
An introduction to IGBTs	AN4503
IGBT ratings and characteristics	AN4504
Heatsink requirements for IGBT modules	AN4505
Calculating the junction temperature of power semiconductors	AN4506
Gate drive considerations to maximise IGBT efficiency	AN4507
Parallel operation of IGBTs – punch through vs non-punch through characteristics	AN4508
Guidance notes for formulating technical enquiries	AN4869
Principle of rating parallel connected IGBT modules	AN5000
Short circuit withstand capability in IGBTs	AN5167
Driving high power IGBTs with Concept gate drivers	AN5190

## POWER ASSEMBLY CAPABILITY

The Power Assembly group provides support for those customers requiring more than the basic semiconductor switch. Using CAD design tools the group has developed a flexible range of heatsink / clamping systems in line with advances in device types and the voltage and current capability of Dynex semiconductors.

An extensive range of air and liquid cooled assemblies is available covering the range of circuit designs in general use today.

## HEATSINKS

The Power Assembly group has a proprietary range of extruded aluminium heatsinks. These were designed to optimise the performance of Dynex semiconductors. Data with respect to air natural, forced air and liquid cooling (with flow rates) is available on request.

For further information on device clamps, heatsinks and assemblies, please contact your nearest sales representative or customer service office.





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**Preliminary Information:** The product is in design and development. The datasheet represents the product as it is understood but details may change.

**Advance Information:** The product design is complete and final characterisation for volume production is well in hand.

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